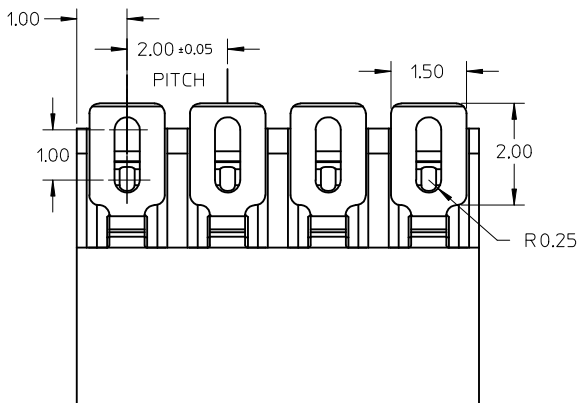


RECOMMENDED PCB LAYOUT  
TOLERANCE: +/- 0.05

NOTE:  
 1.MATERIAL:  
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC,COLOR:BLACK  
 TERMINAL: COPPER ALLOY  
 2.FINISH:  
 CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.  
 SOLDER AREA: GOLD FLASH (0.075~0.125 MICRON) OVER 1.25 MICRON NICKEL MIN.  
 REST AREA: 1.25 MICRON NICKEL MIN.  
 3.COPLANARITY: 0.1 MAX AMONG THESE SOLDER TAILS.  
 4.PRODUCT SPECIFICATION: PS-47286-001  
 5.RECOMMENDED WORKING DEFLECTION RANGE:0.6-1.00 MM



REVISE	EC NO:	2006/09/08	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRWNL:HSHEN	2006/10/17	▽=0					
	CHKD:XIXU	2006/11/16	∇=0					
	APPR:JINCEN							
REV	D			4 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	MOLEX INCORPORATED
			3 PLACES ± --- ± ---	SSUN	2005/07/29	2.0MM PITCH 4 CIRCUITS		
			2 PLACES ± 0.15 ± ---	CHECKED BY	DATE	0.7MM CONTACT WIDTH		
			1 PLACE ± 0.20 ± ---	XUXIANG	2006/07/06	BATTERY CONNECTOR		
			ANGULAR ± 2 °	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
				JENNY CHEN	2006/07/07	472861001	SD-47286-001	1 OF 1
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					A3			